



# PMEG2002AESF

20 V, 0.2 A low VF MEGA Schottky barrier rectifier

10 March 2017

Product data sheet

## 1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection in a DSN0603-2 (SOD962-2) leadless ultra small Surface-Mounted Device (SMD) package.

## 2. Features and benefits

- Average forward current  $I_{F(AV)} \leq 0.2$  A
- Reverse voltage  $V_R \leq 20$  V
- Low forward voltage typ.  $V_F = 245$  mV
- Low reverse current typ.  $I_R = 5$   $\mu$ A
- Ultra small and leadless SMD package
- Package height typ. 0.3 mm

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Low power consumption applications
- Ultra high-speed switching
- LED backlight for mobile application



## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_F$	forward current	$T_{sp} \leq 120$ °C	-	-	0.28	A
$V_R$	reverse voltage	$T_j = 25$ °C	-	-	20	V
$V_F$	forward voltage	$I_F = 200$ mA; $t_p \leq 300$ $\mu$ s; $\delta \leq 0.02$ ; pulsed; $T_j = 25$ °C	-	375	420	mV
$I_R$	reverse current	$V_R = 10$ V; $T_j = 25$ °C	-	5	-	$\mu$ A

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 <p>Transparent top view DSN0603-2 (SOD962-2)</p>	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG2002AESF	DSN0603-2	Leadless ultra small package; 2 terminals; body 0.6 x 0.3 x 0.3 mm	SOD962-2

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG2002AESF	A

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	$T_j = 25\text{ °C}$		-	20	V
$I_F$	forward current	$T_{sp} \leq 120\text{ °C}$		-	0.28	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{amb} = 115\text{ °C}$ ; square wave	[1]	-	0.2	A
		$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{sp} = 125\text{ °C}$ ; square wave		-	0.2	A
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1\text{ ms}$ ; $\delta \leq 0.25$		-	2	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$ ; square wave		-	4.5	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2]	-	325	mW
			[3]	-	525	mW

Symbol	Parameter	Conditions		Min	Max	Unit
			[1]	-	950	mW
$T_j$	junction temperature			-	125	°C
$T_{amb}$	ambient temperature			-55	125	°C
$T_{stg}$	storage temperature			-65	150	°C

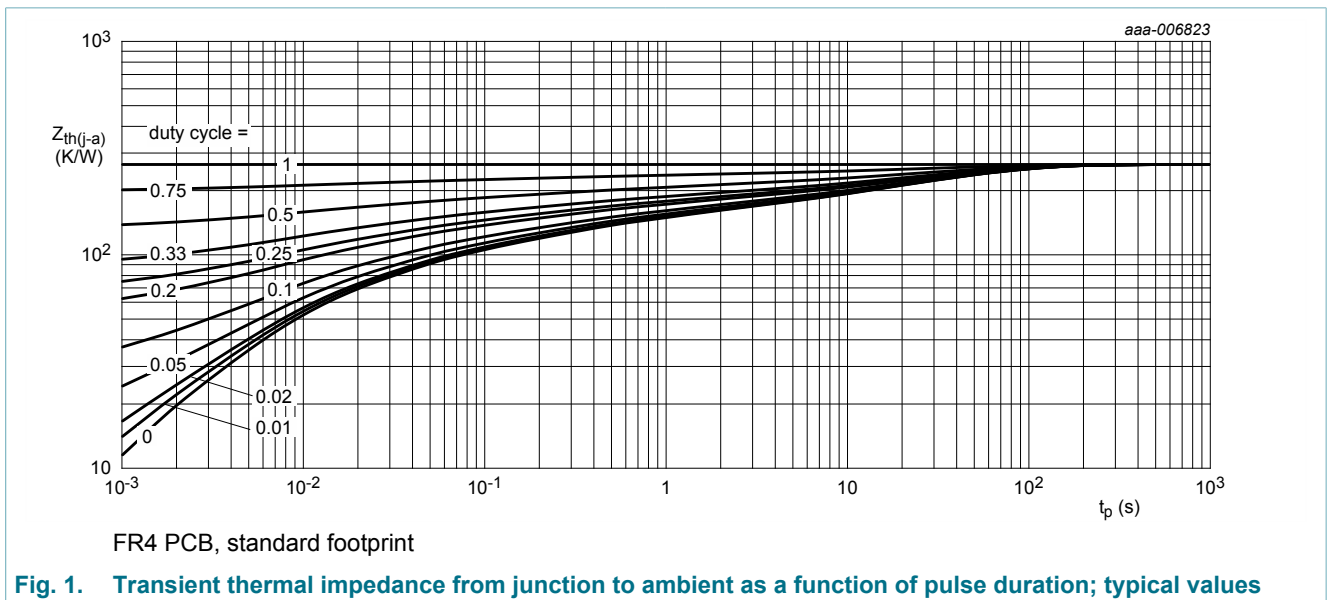
- [1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for anode and cathode 1 cm<sup>2</sup> each.

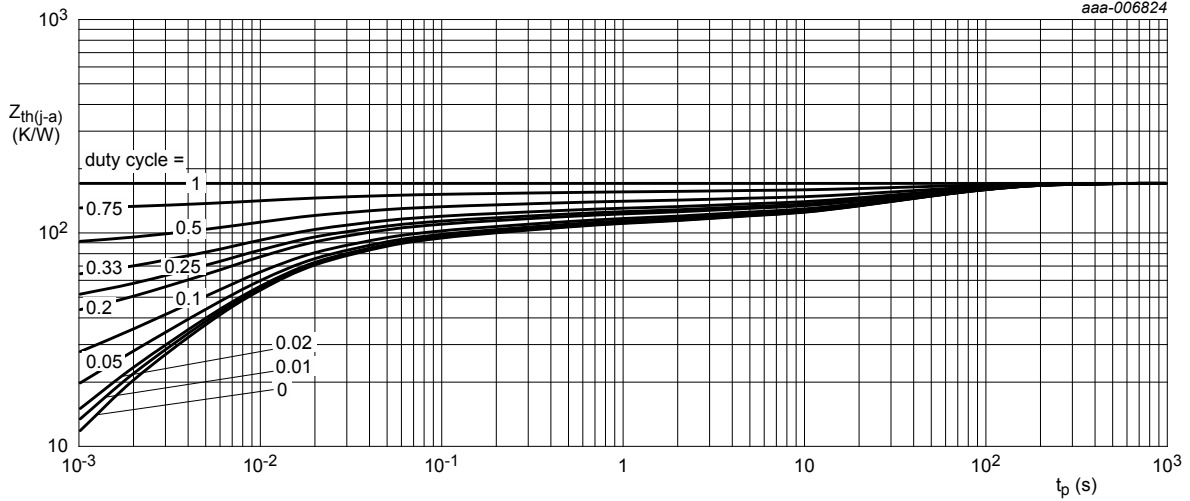
## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	310	K/W
			[1] [3]	-	-	190	K/W
			[1] [4]	-	-	105	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	40	K/W

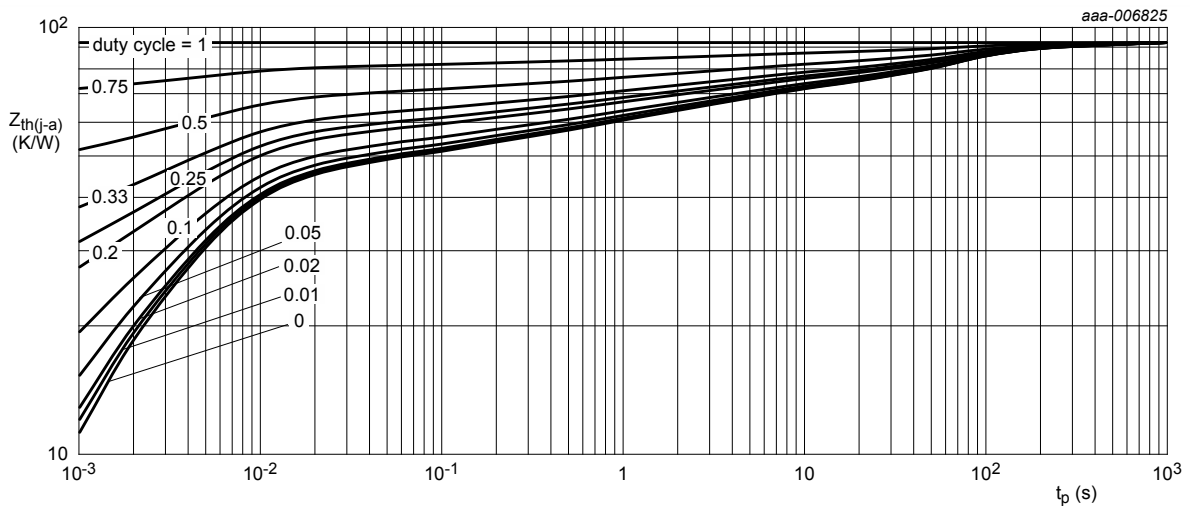
- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for anode and cathode 1 cm<sup>2</sup> each.
- [4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [5] Soldering point of cathode tab.





FR4 PCB, mounting pad for anode and cathode 1 cm<sup>2</sup> each

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

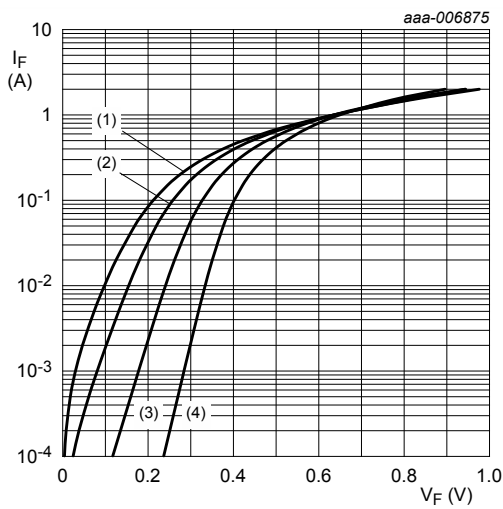
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

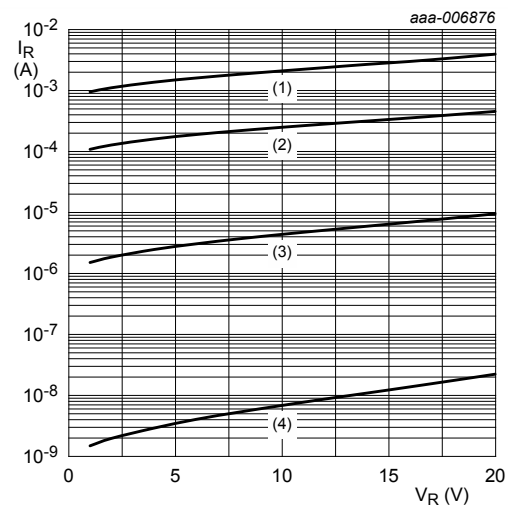
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.1 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; pulsed; T <sub>J</sub> = 25 °C	-	120	180	mV
		I <sub>F</sub> = 1 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; pulsed; T <sub>J</sub> = 25 °C	-	180	250	mV
		I <sub>F</sub> = 10 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; pulsed; T <sub>J</sub> = 25 °C	-	245	310	mV
		I <sub>F</sub> = 100 mA; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; pulsed; T <sub>J</sub> = 25 °C	-	330	380	mV

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
		$I_F = 200 \text{ mA}; t_p \leq 300 \text{ } \mu\text{s}; \delta \leq 0.02$ ; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	-	375	420	mV
$I_R$	reverse current	$V_R = 6 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	3.2	20	$\mu\text{A}$
		$V_R = 10 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	5	-	$\mu\text{A}$
		$V_R = 20 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	10	45	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$	-	25	-	pF
		$V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$	-	10	-	pF
$t_{rr}$	reverse recovery time	$I_F = 200 \text{ mA}; I_R = 200 \text{ mA};$ $I_{R(\text{meas})} = 40 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$	-	1.9	-	ns



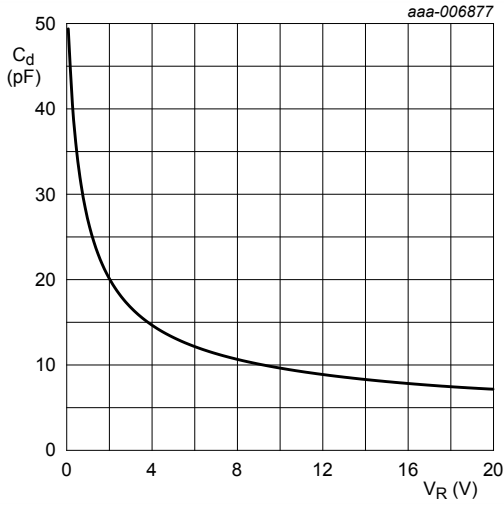
- (1)  $T_j = 125 \text{ }^\circ\text{C}$
- (2)  $T_j = 85 \text{ }^\circ\text{C}$
- (3)  $T_j = 25 \text{ }^\circ\text{C}$
- (4)  $T_j = -40 \text{ }^\circ\text{C}$

Fig. 4. Forward current as a function of forward voltage; typical values

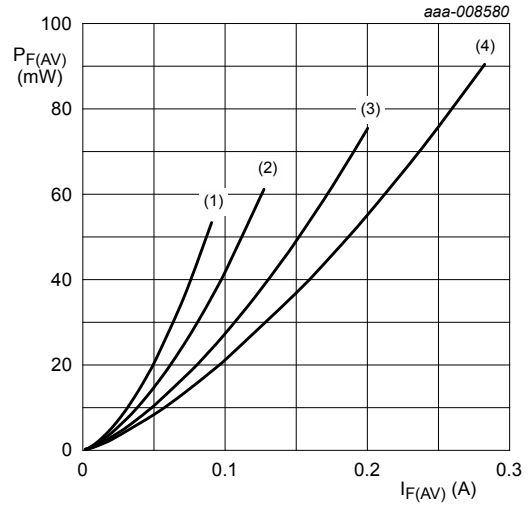


- (1)  $T_j = 125 \text{ }^\circ\text{C}$
- (2)  $T_j = 85 \text{ }^\circ\text{C}$
- (3)  $T_j = 25 \text{ }^\circ\text{C}$
- (4)  $T_j = -40 \text{ }^\circ\text{C}$

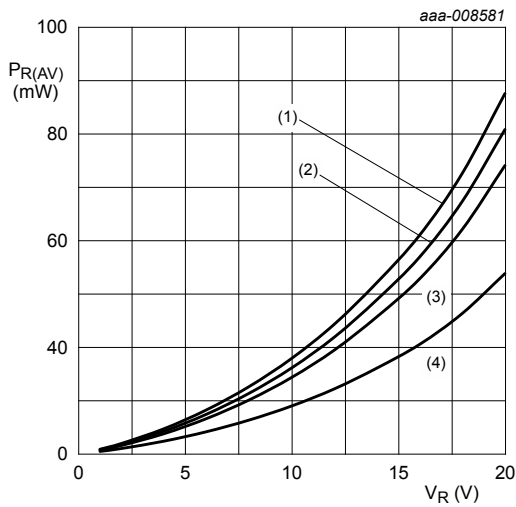
Fig. 5. Reverse current as a function of reverse voltage; typical values



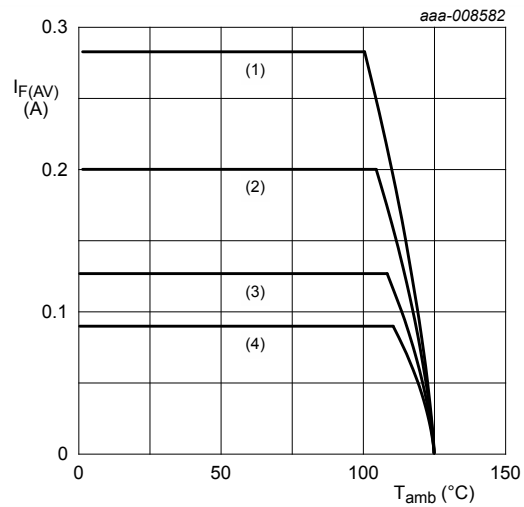
**Fig. 6. Diode capacitance as a function of reverse voltage; typical values**



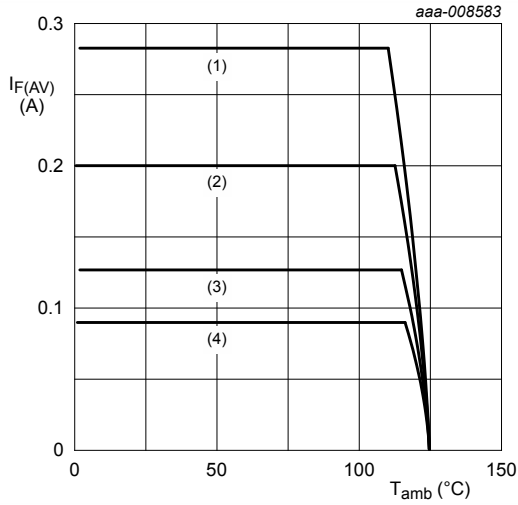
**Fig. 7. Average forward power dissipation as a function of average forward current; typical values**



**Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values**

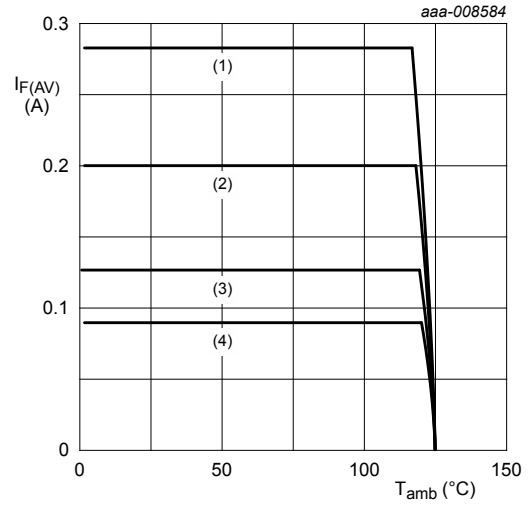


**Fig. 9. Average forward current as a function of ambient temperature; typical values**



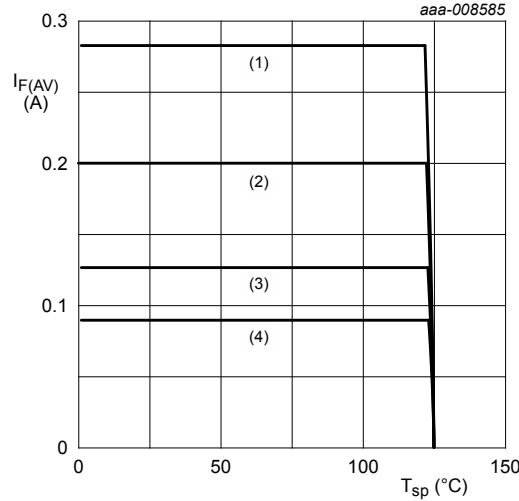
FR4 PCB, mounting pad for anode and cathode 1 cm<sup>2</sup> each  
 $T_j = 125\text{ °C}$   
 (1)  $\delta = 1$   
 (2)  $\delta = 0.5$   
 (3)  $\delta = 0.2$   
 (4)  $\delta = 0.1$

**Fig. 10. Average forward current as a function of ambient temperature; typical values**



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint  
 $T_j = 125\text{ °C}$   
 (1)  $\delta = 1$   
 (2)  $\delta = 0.5$   
 (3)  $\delta = 0.2$   
 (4)  $\delta = 0.1$

**Fig. 11. Average forward current as a function of ambient temperature; typical values**



$T_j = 125\text{ °C}$   
 (1)  $\delta = 1$   
 (2)  $\delta = 0.5$   
 (3)  $\delta = 0.2$   
 (4)  $\delta = 0.1$

**Fig. 12. Average forward current as a function of solder point temperature; typical values**

### 11. Test information

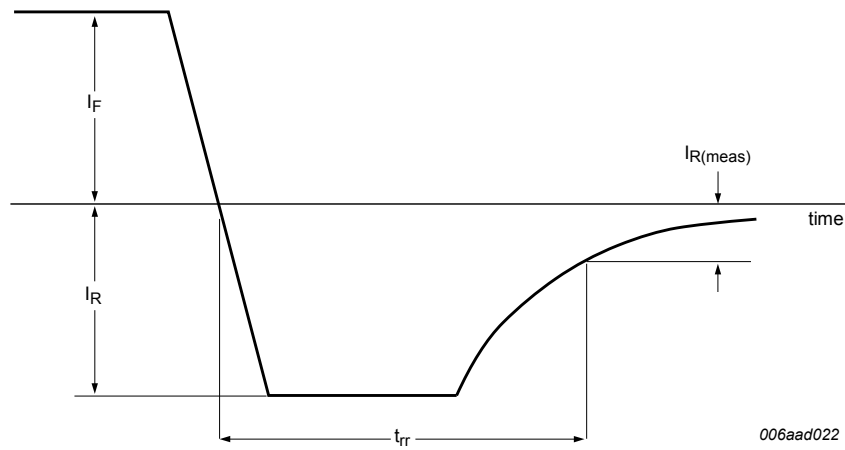


Fig. 13. Reverse recovery definition

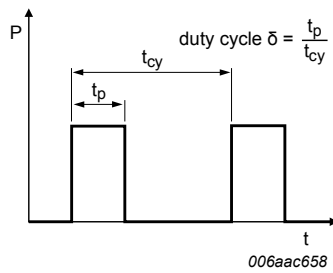


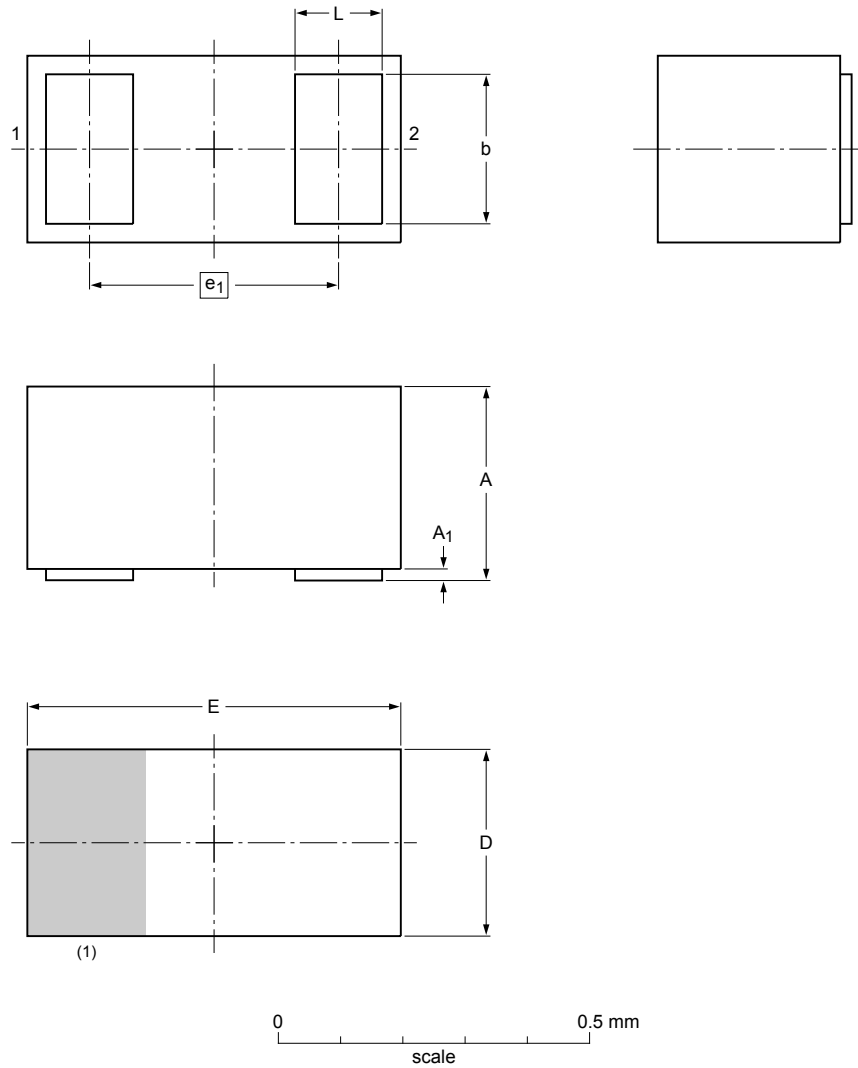
Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:  $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.



## 12. Package outline

Leadless ultra small package; 2 terminals; body 0.6 x 0.3 x 0.3 mm SOD962-2



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	b	D	E	e <sub>1</sub>	L
mm	max	0.32	0.03	0.25	0.325	0.625	0.15
	nom					0.4	
	min	0.28		0.23	0.275	0.575	0.13

Note

1. The marking bar indicates the cathode.

sod962-2\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOD962-2					-13-07-12- 13-07-17

Fig. 15. Package outline DSN0603-2 (SOD962-2)

### 13. Soldering

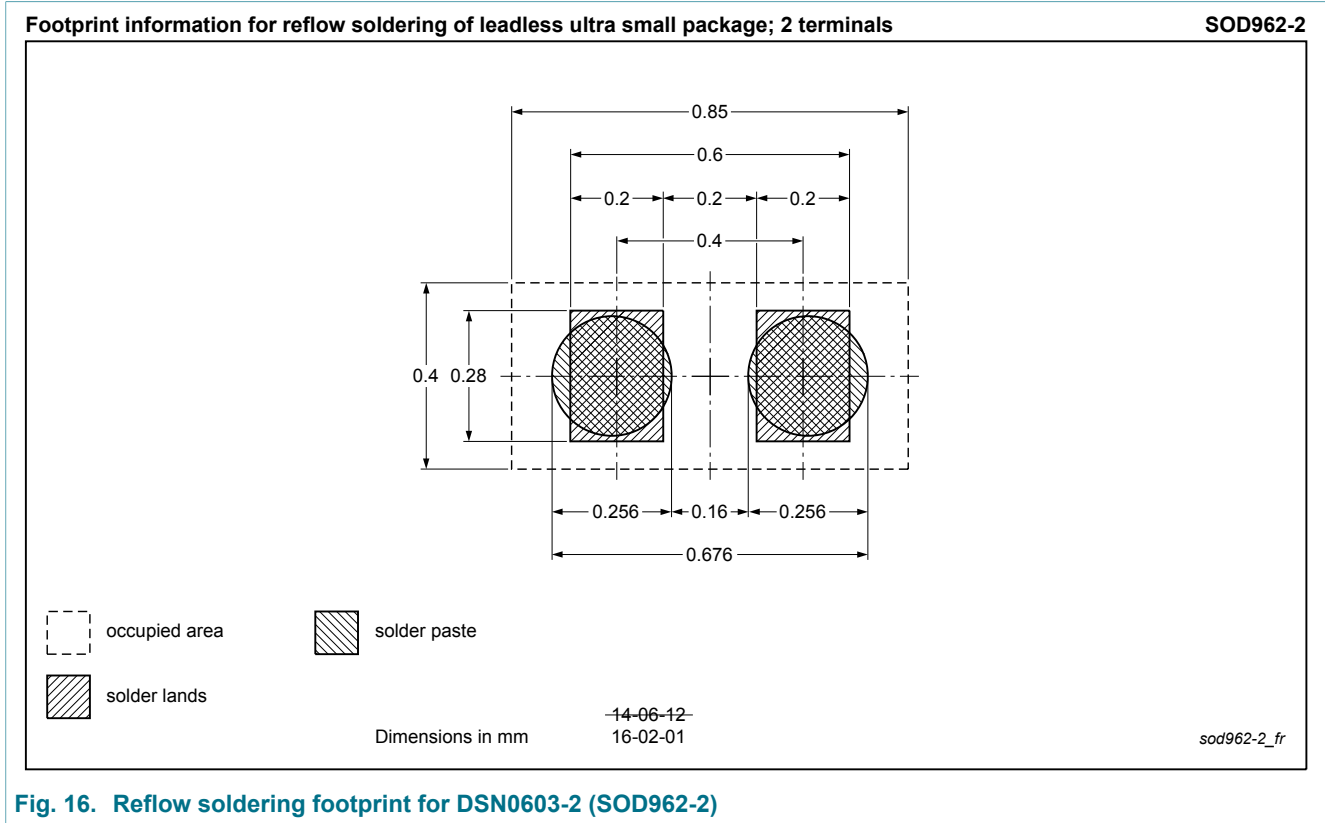


Fig. 16. Reflow soldering footprint for DSN0603-2 (SOD962-2)

### 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2002AESF v.3	20140122	Product data sheet	-	PMEG2002AESF v.2
Modifications:	<ul style="list-style-type: none"> <li>Features and benefits: corrected</li> </ul>			
PMEG2002AESF v.2	20131008	Product data sheet	-	PMEG2002AESF v.1
PMEG2002AESF v.1	20130301	Objective data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
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